

WHAT IS CLAIMED IS:

1. A housing for electronic equipment comprising:

a metal base board having at least one through holes;

one or more components that are joined to the metal base board by outsert-molding; and

one or more side walls in which said metal base board and said one or more components are joined,

wherein at least one part of a terminal part of said metal base board at one or more side walls is formed in a convex shape which is not joined to said components.

2. A housing for electronic equipment comprising:

a metal base board;

one or more components that are joined to the metal base board by outsert-molding; and

one or more side walls in which said metal base board and said one or more components are joined,

wherein at least one part of a terminal part of said metal base board at one or more side walls is formed in a concave shape.

3. A housing for electronic equipment comprising:

a metal base board; and

one or more components that are joined to the metal base board by outsert-molding; and

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in a range of 8% to 12%.

6. A housing for electronic equipment comprising:

a metal base board;

one or more components that are joined to the metal base board by outsert-molding; and

a side wall,

wherein said components are joined to whole of one surface of said metal base board except for at least the side wall, and a ratio of thickness of said metal base board to total thickness of the housing is in a range of 30% to 50%.

7. The housing for electronic equipment according to claim 1, wherein a development shape of said metal base board has at least one through hole, and has a notch of an arbitrary angle at one or more corners of the development shape.

8. The housing for electronic equipment according to claim 6, wherein a development shape of said metal base board has at least one through hole, and has a notch of an arbitrary angle at one or more corners of the development shape.

9. The housing for electronic equipment according to claim 1, wherein on a surface of said component attached on said metal base board, said component is formed in a concave shape at at least one of portions corresponding to said through holes of said metal base board.

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10. A manufacturing method of a housing for electronic equipment including a metal base board and one or more components that are joined to the metal base board by outsert-molding, comprising the steps of:

forming said components on a surface of said metal base board opposite to a gate for the outsert-molding by synthetic resin injection from the gate provided at a position where synthetic resin can be injected through at least one through hole of said base board; and

bending and processing side walls of the housing by pressure of injection of synthetic resin.

11. A manufacturing method of a housing for electronic equipment including a metal base board and one or more components that are joined to the metal base board by outsert-molding,

wherein as a method of fixing said metal base board to a die when forming said components on a surface of the metal base board opposite to a gate for the outsert-molding by synthetic resin injection from the gate provided at a position where synthetic resin can be injected through at least one through hole of said metal base board, a positioning pin is provided to at least one of said through holes.

12. The manufacturing method of a housing for electronic equipment according to claim 11,

wherein vacuum-pull is used for fixing said base board onto the die.

13. Electronic equipment comprising a housing for electronic equipment according to claim 1.

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